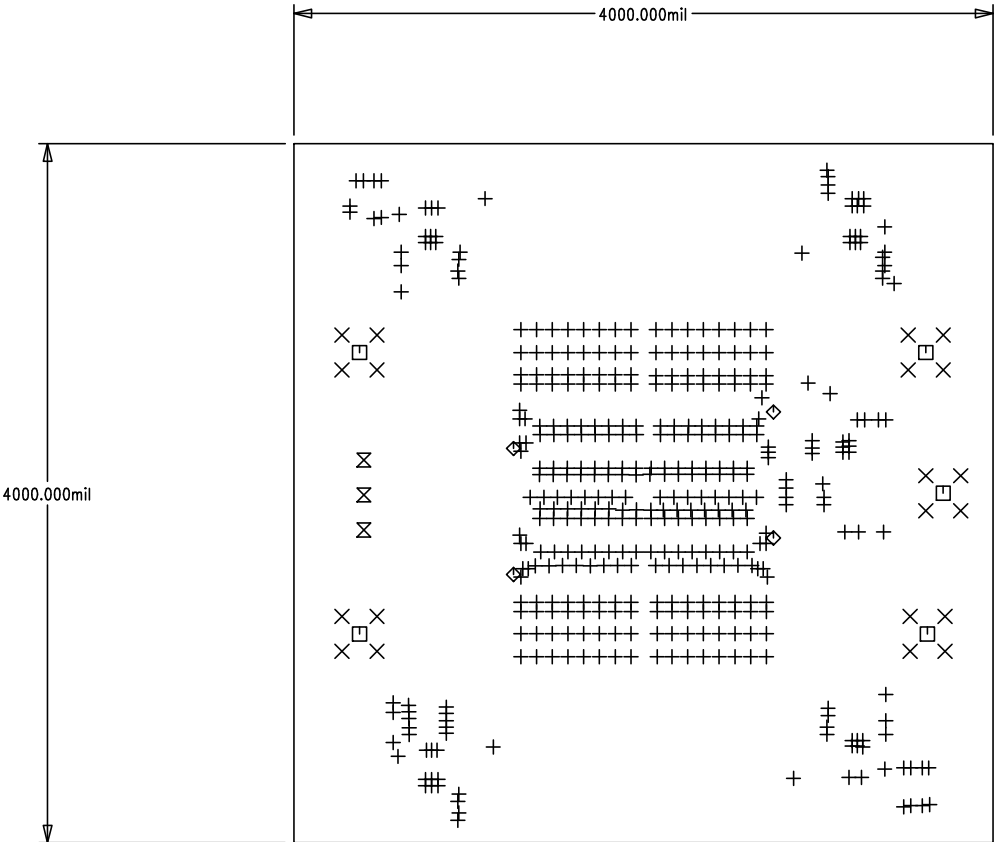
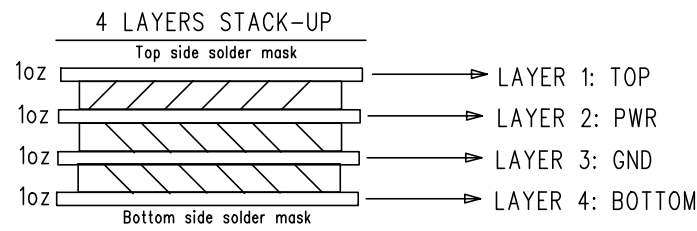


SIZE	QTY	SYM	PLATED	TOL
10	423	+	YES	+/-3.0
66.93	20	✕	YES	+/-3.0
46.06	5	□	YES	+/-3.0
35.43	4	◇	NO	+/-2.0
59.06	3	⊗	YES	+/-3.0



- FAB NOTES:
- Materials: 370HR or equivalent, see cross section for board thickness, copper weight and layer structures.
 - Components on the top layer and bottom layer .
 - Minimum signal trace width/spacing : 6/6 mils
 - Drilling
 - minimum hole size is 10 mils drill
 - all plated holes are to be plated thru and with min .001" thick
 - all hole diameters are finished sizes
 - all holes to be +/-0.003" from true position unless otherwise specified for PTH, or +/-0.002" if it's NPTH
 - NC drill file has been supplied, see hole size table.
 - Front to back(pattern shall register within .005"
 - Layer to layer(pattern to pattern) registration to be +/-0.005"
 - Soldermask: Both sides of board, Liquid Photo Imageable, soldermask over bare copper (SMOBC), green
 - Warpage and twist to meet IPC class II
 - Silkscreen using white non-conductive epoxy or equivalent
 - Finish:
 - Edge to be free of loose sliver and rough edge
 - Finished board shall not have nicks scratches, voids, exposed copper, poor plating or misdrilled holes
 - Trace width tol=+/-0.001" of finished trace width
 - Standard HASL or Silver is OK
 - Date code and UL rating shall be permanently marked or etched on PCB
 - Remove non-functional pad in inner layers and planes



Overall Thickness 62 mils +/- 10%

FAB_DWG